

Mixed Signal System

Mixed Signal Integrated Circuit

any integrated circuit that has both analog circuits and digital circuits on a single semiconductor die.

Embedded System

a computer system—computer processor + memory + I/O peripheral devices—that has a dedicated function within a stand-alone product or as a sub-function within a larger system.

D/A Conversion Topics

DAC quantization: Conversion of binary-value input signals to a discrete-value output voltage
Resolution: Defines the # of discrete quantized levels resolved by the converter

DAC resolution

Bit resolution, N, equals the number of binary-weighted DAC inputs
Voltage Resolution, $V_{LSB} = V_{REF}/2^N$ smallest resolvable V_{OUT} value
divides the V_{REF} range into 2^N discrete values

$$\text{Full-scale } V_{OUT} = V_{LSB} * (2^N - 1) = V_{REF} - V_{LSB}$$
$$V_{OUT} = V_{LSB} * (\text{Input code})_d = (V_{REF}/2^N) * (\text{Input code})_d$$



For a 4-bit D/A converter with $V_{REF} = 16V$

What is the V_{LSB} $V_{LSB} = 16V/16 = 1V$
What is the V_{FS} $V_{FS} = 1V * 15 = 16V - 1V = 15V$
What is V_{OUT} @ $B = 0x2$ $V_{OUT} = 1V * 2_{DECIMAL} = 2V$
What is V_{OUT} @ $B = 0x8$ $V_{OUT} = 1V * 8_{DECIMAL} = 8V$
What is V_{OUT} @ $B = 0xC$ $V_{OUT} = 1V * 12_{DECIMAL} = 12V$

Binary-Weighted DAC Inputs

$B_3 = 1 \Rightarrow V_{REF}/2$
 $B_2 = 1 \Rightarrow V_{REF}/4$
 $B_1 = 1 \Rightarrow V_{REF}/8$
 $B_0 = 1 \Rightarrow V_{REF}/16$

A/D Conversion Topics

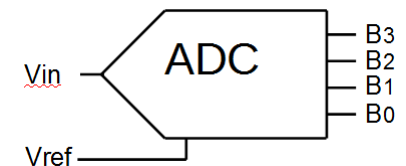
ADC quantization: Conversion of continuous-value input signals to discrete-value binary out
Resolution: Defines the # of discrete quantized levels resolved by the converter.

ADC resolution

Bit resolution, N, equals the number of binary-weighted ADC outputs
Voltage Resolution, $V_{LSB} = V_{REF}/2^N$ smallest resolvable V_{IN} value
divides the V_{REF} range into 2^N discrete values

$$\text{Full-scale } V_{IN} = V_{LSB} * (2^N - 1) = V_{REF} - V_{LSB}$$
$$B_{OUT}^{**} = (V_{IN}/V_{LSB})_b = (2^N * V_{IN}/V_{REF})_b \text{ ranges from } 0 \text{ to } 2^N - 1 \text{ binary}$$

** round to nearest integer value (quantization error)



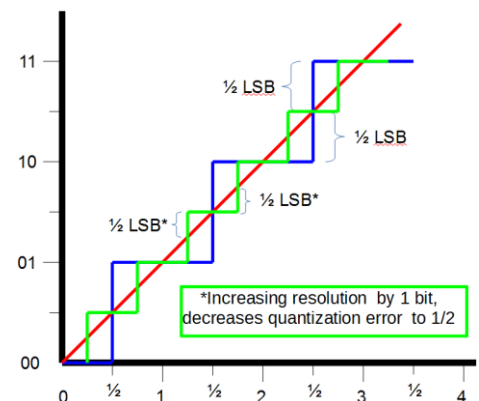
A/D quantization error:

Difference between the input analog signal & the closest equivalent discrete digital output value at each sampling instant.

Quantization error introduces noise - quantization noise - to the sample signal.
Increasing the resolution decreases the quantization noise.

For a 4-bit A/D converter with $V_{REF} = 5V$

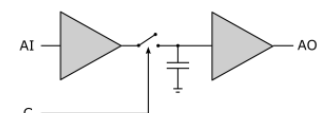
What is the V_{LSB} $V_{LSB} = 5V/16 = 0.3125V$
What is the V_{FS} $V_{FS} = 0.3125V * 15 = 5V - 0.3125V = 4.6875V$
What is B_{OUT} @ $V_{IN} = 0.625V$ $B_{OUT} = 0.625V/0.3125V = 2_{DECIMAL} = 0x2$
What is B_{OUT} @ $V_{IN} = 2.500V$ $B_{OUT} = 2.500V/0.3125V = 8_{DECIMAL} = 0x8$
What is B_{OUT} @ $V_{IN} = 3.750V$ $B_{OUT} = 3.750V/0.3125V = 12_{DECIMAL} = 0xC$



Sample-Hold

Captures and stores an instantaneous sample of an analog signal for a specified time.
Uses a switched capacitor circuit.

Acquisition time min time required to acquire the sample to the specified accuracy
Voltage Droop rate of voltage decay per time, ie $\mu V/\mu S$.



Resistor Ladder Nets

String Ladder:

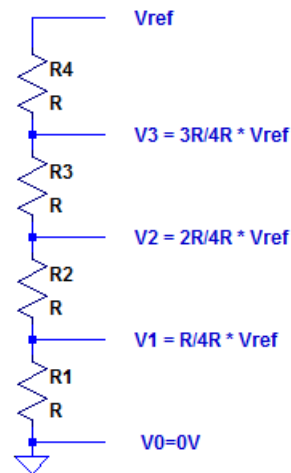
voltage divider used for A/D Flash conversion
requires 2^N resistors to achieve an N-bit conversion
partitions V_{REF} into 2^N discrete values

With equal value resistors R

$$V_{LSB} = V_{REF}/2^N$$

$$V_{OUT} \text{ (full-scale)} = V_{LSB} * (2^N - 1) = V_{REF} - V_{LSB}$$

simple network, implements fast A/D conversion
but requires 2^N resistors to achieve an N-bit conversion



2-Bit example, 4 Resistors, V_{LSB} is $V_{REF}/4$

R-2R Ladder:

voltage divider used for D/A conversion
requires $2*N$ resistors to achieve an N-bit conversion
N equals the # of R-2R inputs, a_0 - a_{N-1} .

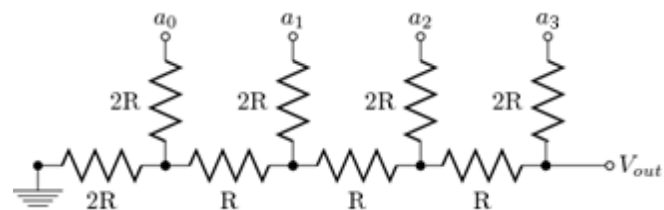
partitions V_{REF} into 2^N discrete values

$$V_{LSB} = V_{REF}/2^N$$

$$V_{OUT} = V_{LSB} * (\text{Input code})_d = (V_{REF}/2^N) * (\text{Input code})_d$$

$$V_{OUT} \text{ (full-scale)} = V_{LSB} * (2^N - 1) = V_{REF} - V_{LSB}$$

Output impedance is equal to R, regardless of the number of bits, or the binary input code
two resistor values facilitates fabrication and integration



4-Bit R-2R Ladder Network

V_{REF} is applied to the R-2R inputs in a binary-encoded manner that is, binary levels, $a_x=0$ or $a_x=V_{REF}$

Binary-Weighted DAC Inputs

$$V_{REF} \text{ @ } a_0: V_{LSB} * 2^0 = 1 * V_{LSB} \quad \text{OR } V_{REF}/2^N = V_{REF}/16 \quad \text{LSB}$$

$$V_{REF} \text{ @ } a_1: V_{LSB} * 2^1 = 2 * V_{LSB} \quad \text{OR } V_{REF}/2^{N-1} = V_{REF}/8$$

$$V_{REF} \text{ @ } a_2: V_{LSB} * 2^2 = 4 * V_{LSB} \quad \text{OR } V_{REF}/2^{N-2} = V_{REF}/4$$

$$V_{REF} \text{ @ } a_3: V_{LSB} * 2^3 = 8 * V_{LSB} \quad \text{OR } V_{REF}/2^{N-3} = V_{REF}/2 \quad \text{MSB}$$

$$0V \text{ applied to any input contributes } 0V$$

Inputs are additive to V_{OUT} and independent of the others.

$$V_{OUT} = V_{LSB} * (\text{Input code})_d = (V_{REF}/2^N) * (\text{Input code})_d$$

4-bit Example

If $V_{REF} = 16V$ and assuming the following binary-encoded values, $a_{(3-0)}$, what is V_{OUT}

$$a_{(3-0)} = 0xC = 1100_b \quad V_{OUT} = 8 * V_{LSB} + 4 * V_{LSB} = 8 * 1V + 4 * 1V = 12V$$

$$a_{(3-0)} = 0x8 = 1000_b \quad V_{OUT} = 8 * V_{LSB} = 8 * 1V = 8V$$

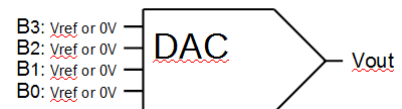
$$a_{(3-0)} = 0x3 = 0011_b \quad V_{OUT} = 2 * V_{LSB} + 1 * V_{LSB} = 2 * 1V + 1 * 1V = 3V$$

Using $V_{OUT} = V_{LSB} * (\text{Input code})_d$

$$a_{(3-0)} = 0xC = 1100_b \quad V_{OUT} = 1V * (0xC)_d = 1V * 12 = 12V$$

$$a_{(3-0)} = 0x8 = 1000_b \quad V_{OUT} = 1V * (0x8)_d = 1V * 8 = 8V$$

$$a_{(3-0)} = 0x3 = 0011_b \quad V_{OUT} = 1V * (0x3)_d = 1V * 3 = 3V$$

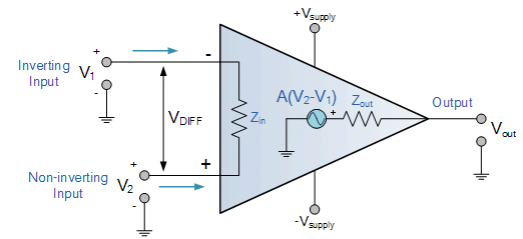


OpAmp Topics

The operational amplifier is a high gain difference amplifier.

$$V_O = A_V (V_+ - V_-)$$

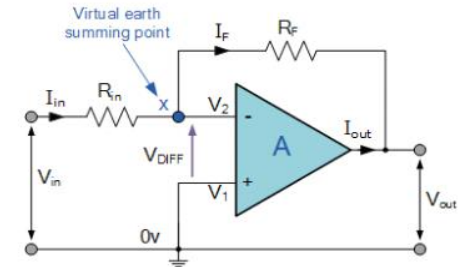
| | |
|--------------------------|--|
| Differential Input | $V_+ - V_-$ |
| Open-loop gain | High, $A_V \sim 100,000$ |
| Input impedance | High, $\sim 100\text{K}\Omega$ to $>1\text{G}\Omega$ |
| Open-loop Output Z | Low, varies, maybe 100Ω |
| Assume: infinite input Z | zero output Z |



Inverting Amp

Circuit gain, $A_V = V_O / V_{IN} = -(R_F / R_{IN})$

$$V_O = -V_{IN} * (R_F / R_{IN}) = -V_{IN} * A_V$$

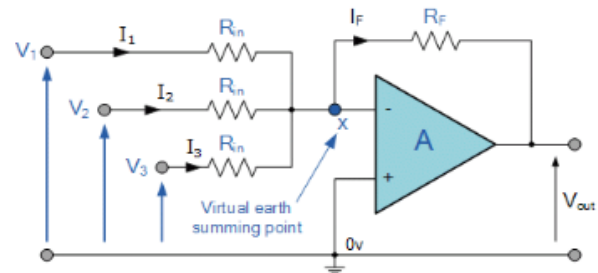


Inverting Summing Amp

$$V_O = -(V_1 A_{V1} + V_2 A_{V2} + V_3 A_{V3})$$

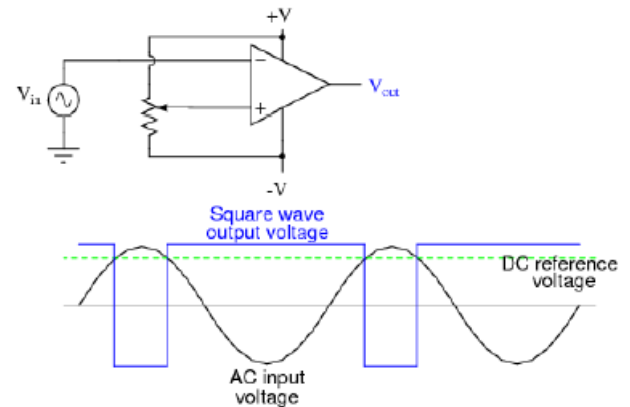
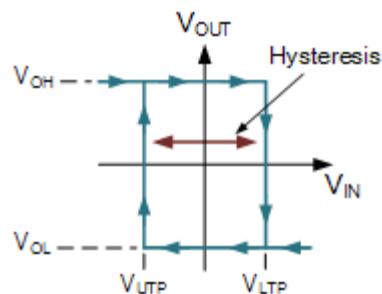
IF $V_1 = V_2 = V_3 = V_{IN}$,

$$V_O = -V_{IN} * (R_F / R_{IN1} + R_F / R_{IN2} + R_F / R_{IN3}) = -V_{IN} * (A_{V1} + A_{V2} + A_{V3})$$



Comparator

The comparator output switches, $+V_{CC}$ to $-V_{CC}$, in the direction of the larger input voltage.



Inverting Integrator (aka Ramp Generator)

A step voltage at the input will generate a ramp voltage at the output

Capacitor voltage equals charge (Q Coulombs) divided by capacitance (C Farads)

that is $1V = 1Q / 1F$ or $V_{CAP} = Q / C$

Current (I) is defined as $1Amp = 1Q / 1Sec$ (ie charge flow per time)

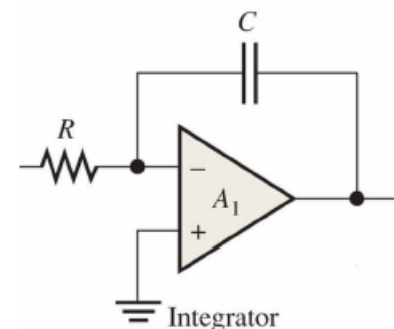
So... $1Q = 1Amp * 1Sec$ or $Q = I * t$

Substitute $I * t$, $V_{CAP} = I * t / C$

For the Inv Integrator let $R = 1\Omega$ $C = 1F$ $V_{IN} = 1V$ $V_{CAP} = V_{OUT}$ $I_{IN} = V_{IN} / R$

$$V_{OUT} = -(V_{IN} / R) * t / C \quad (V_{OUT} \text{ after } t \text{ sec with } V_{IN} \text{ applied})$$

$$t = -V_{OUT} * C / (V_{IN} / R) \quad (\text{time required for } V_{OUT} \text{ to ramp to } V_{IN})$$



Example: 4-bit Binary-Weighted D/A Converter

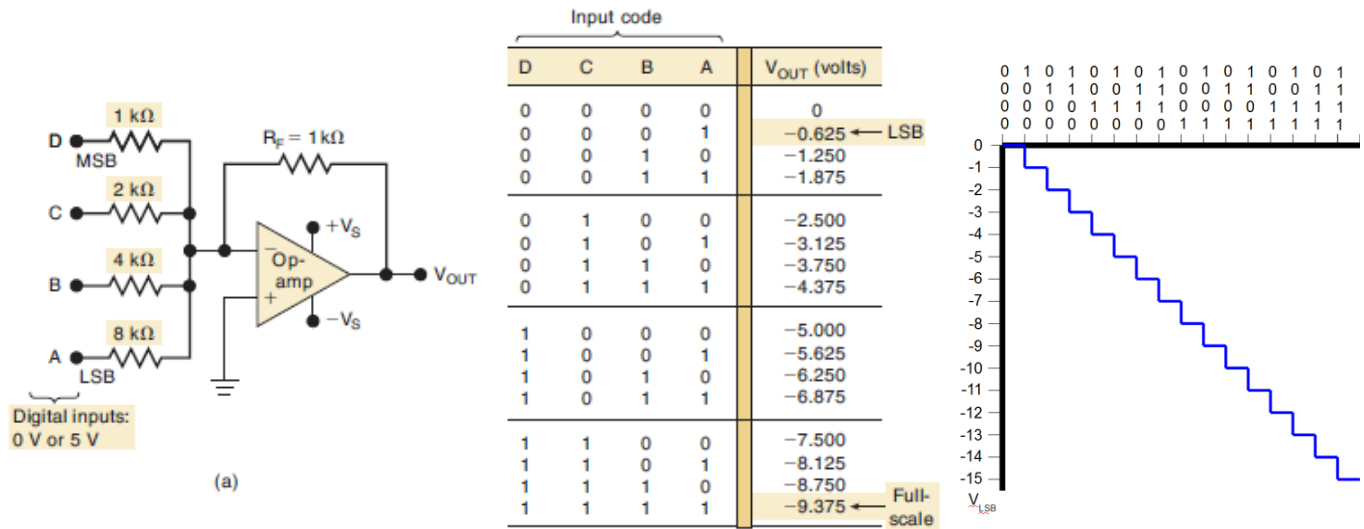


Fig 11.5 Ref Digital Systems textbook Ch 11.3 DAC Circuitry

4-bit DAC with binary-weighted input resistors & $V_{ref} = 5V$

$A_{v\text{ LSB}} = -1/8$ $A_{v\text{ MSB}} = -1$

$$V_O = -(V_{REF}A_{VA} + V_{REF}A_{VB} + V_{REF}A_{VC} + V_{REF}A_{VD})$$

$$V_O = -V_{REF} * (A_{VA}[B_A] + V_{REF}A_{VB}[B_B] + V_{REF}A_{VC}[B_C] + V_{REF}A_{VD}[B_D])$$

$$V_{LSB} = V_{REF} * (-1/8) = -0.625V$$

$$V_{MSB} = V_{REF} * (-1) = -5V$$

$$V_{FS} = -5V - 2.5V - 1.25V - 0.625V = -9.375V$$

For this Binary-Weighted DAC:

$$V_{REF} = 5V$$

$$V_O = -V_{REF} * (A_{V2}B_3 + A_{V2}B_2 + A_{V1}B_1 + A_{V0}B_0)$$

What is V_{LSB} ?

$$V_{LSB} = -5V * [0 + 0 + 0 + (1/16)] = -0.3125V$$

What is V_{OUT} when the V_{REF} input is binary-encoded as 0x8 (1000b)?

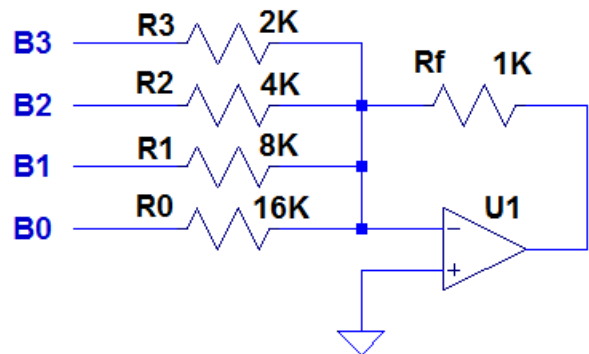
$$V_{OUT} = -5V * ((1/2) + 0 + 0 + 0) = -2.5V$$

What is V_{OUT} when the V_{REF} input is binary-encoded as 0xC (1100b)?

$$V_{OUT} = -5V * ((1/2) + (1/4) + 0 + 0) = -3.75V$$

What is V_{FS} ?

$$V_{FS} = -5V * ((1/2) + (1/4) + (1/8) + (1/16)) = -4.6875V$$



Limited resolution:

Resistor value range can span several orders of magnitude for medium resolution.

At 12-bit, if $R_{MSB} = 1K\Omega$ $R_{LSB} = 2M\Omega$

The fabrication of precision IC resistances over a large range of values is problematic - difficult to maintain an accurate R ratio over temperature variation.

Example: 4-bit R-2R D/A Converter

Thevenin Equivalent of the R2R DAC

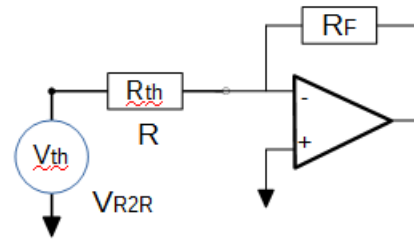
<https://www.best-microcontroller-projects.com/R-2R-ladder.html>

Thevenin equivalent circuit gain :

$$A_V = -R_F/R_{TH}$$

Thevenin equivalent V_{R2R} :

$$\begin{aligned} V_{TH} &= V_{LSB} * (\text{Input Code})_d \\ &= (V_{REF}/2^N) * (\text{Input Code})_d \end{aligned}$$



Example R2R DAC: $V_{REF} = 5V$

What is V_{OUT} when the V_{REF} input is binary-encoded as 0x8 (1000b)?

$$\begin{aligned} V_{OUT} &= A_{VTH} * V_{TH} \\ &= -(R_F/R_{TH}) * (V_{REF}/2^N) * (\text{Input Code})_d \\ &= (-1) * (5V/16) * (8) = -2.5V \end{aligned}$$

What is V_{OUT} when the V_{REF} input is binary-encoded as 0xC (1100b)?

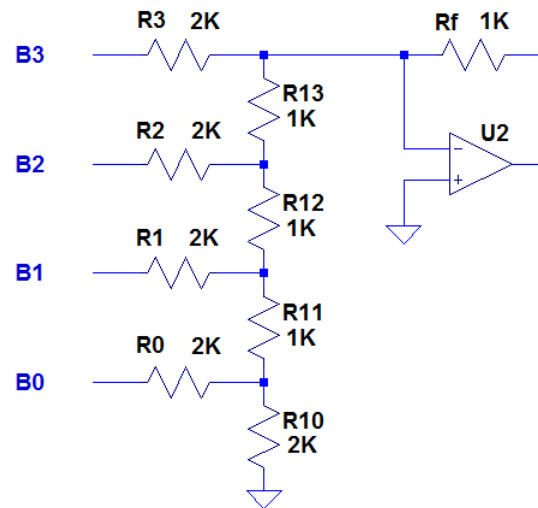
$$V_{OUT} = (-1) * (5V/16) * (12) = -3.75V$$

What is V_{FS} ?

$$= (-1) * (5V/16) * (15) = -4.6875V$$

4-bit R2R Ladder binary-weighted input:

| | | | |
|-------------------|----------------------|----|--------------|
| V_{REF} @ B_3 | $V_{OUT} = 8V_{LSB}$ | OR | $V_{REF}/2$ |
| V_{REF} @ B_2 | $V_{OUT} = 4V_{LSB}$ | OR | $V_{REF}/4$ |
| V_{REF} @ B_1 | $V_{OUT} = 2V_{LSB}$ | OR | $V_{REF}/8$ |
| V_{REF} @ B_0 | $V_{OUT} = 1V_{LSB}$ | OR | $V_{REF}/16$ |



Memory Topics

Volatile mem – SRAM, DRAM

Volatile memory retains memory only when power to the memory is on.

Static – retains data indefinitely with power on.

Dynamic – retains data temporarily with power on.

Simpler cells than NVM, 6T-4T-1T1C smaller, faster, less expensive, used for the main memory in most computers.

Non-Volatile mem – ROM, PROM, EPROM, EEPROM, Flash

NVM Retains memory when power to the memory is off.

Non-volatile semiconductor memory (NVM, since EPROM) stores data in floating-gate MOSFET memory cells.

ROM – fixed memory, no write capability, photo-lithographic mask during IC fab

PROM – one-time programmable (OTP), fixed thereafter, originally fuse-based technology

EPROM – programmable, UV erasable - complete memory array only

EEPROM – programmable, electrically erasable - any individual addressable location - via control logic & prog voltage

Flash – >10 yr retention, finite WR endurance up to 1M, WR/Erase of blocks/sections only

Memory Access Methods

Methods to access memory locations:

1. **Random Access:** each memory location is uniquely accessible in any order and in uniform time.
2. **Sequential Access:** memory access in sequential order - magnetic or optical disk HDs.
3. **Direct Access:** Information is stored in tracks, with each track having a separate read/write head - mag/opt/SSD drives.

EET123 will focus on Random Access

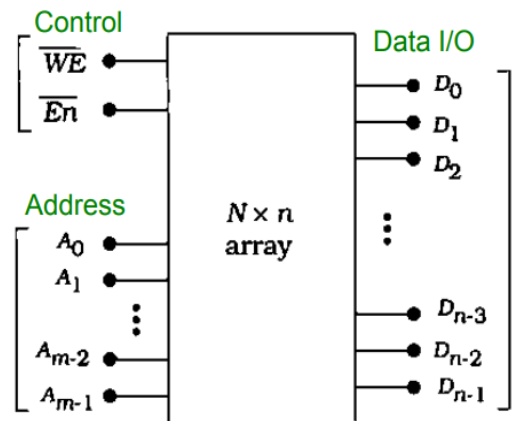
Memory Access - Addressability

Address decoding logic will organize the cell array as $N \times n$

N addressable locations - row logic will uniquely address each data group
 n bit depth - bytes, 16-bit words, 32-bit words, etc

Memory $N \times n$ organization

| | | | | |
|--------|-------------|------------------------|-----------------|-------------|
| 1Kx8: | 8-bit data | 1024 addr locations | 8K bits total | 10-bit addr |
| 1Kx16: | 16-bit data | 1024 addr locations | 16K bits total | 10-bit addr |
| 16Kx8: | 8-bit data | 16384 addr locations | 128K bits total | 14-bit addr |
| 1Mx8: | 8-bit data | 1048576 addr locations | 8M bits total | 20-bit addr |



Memory Cells

SRAM Cell 6T, 4T

Larger/ costs more than DRAM, faster than NVRAM

DRAM Cell 1T1C

Smaller/costs less than SRAM, slower than SRAM, requires refresh

EEPROM Cell Floating-gate MOSFET

Programming techniques, hot electron, Fowler-Nordheim emission

Rd/Wr to individual address location – slower than flash

Flash Cell Floating-gate MOSFET

Rd to individual address location

Wr/Erase large block address locations (sectors) – faster than EEPROM

Harvard Arch vs Von Neumann Arch

The **Von Neumann architecture** exhibits one addr/data bus for both instruction and data memory.

The **Harvard architecture** exhibits one addr/data bus for program memory and a separate addr/data bus for data memory, allowing simultaneous access to both instructions and data.

The **modified Harvard architecture** is a variation of the Harvard computer architecture that, unlike the pure Harvard architecture, allows the contents of the instruction memory to be accessed as data. Most modern computers that are documented as Harvard architecture are, in fact, modified Harvard architecture.

Von Neumann memory address space

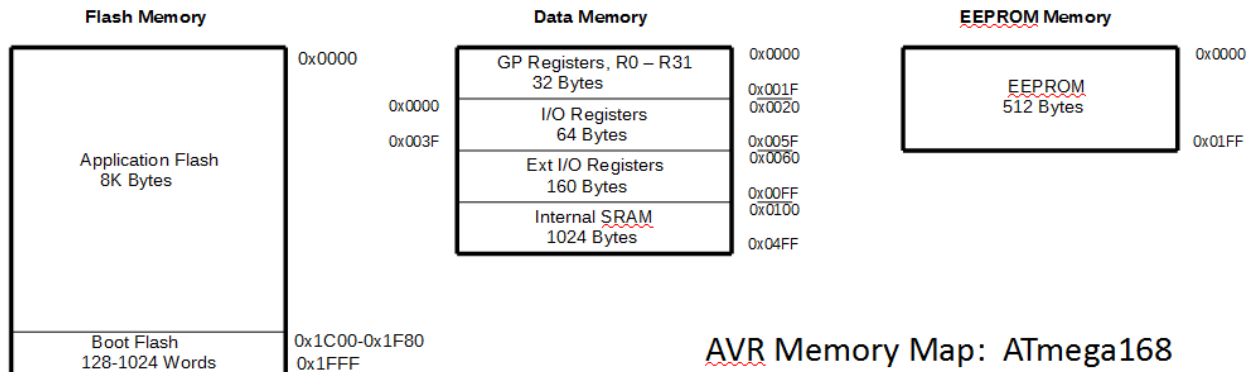
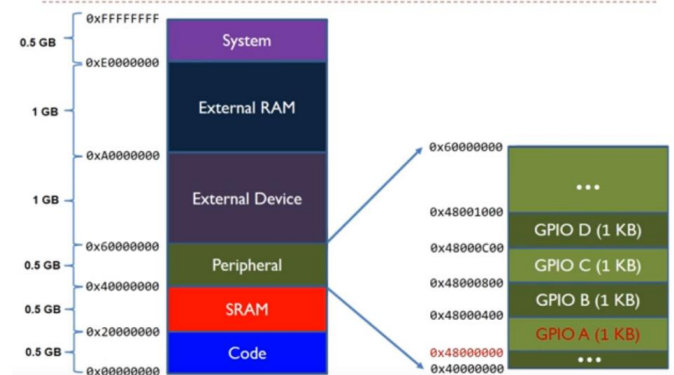
All addressable locations reside within one contiguous address space.

AVR microcontrollers use the Modified Harvard architecture.

Separate memory types connect to separate buses.

| | |
|----------------|--------------------------|
| Program memory | Non-volatile Flash |
| Data memory | Volatile SRAM Data |
| EEPROM memory | Non-volatile EEPROM Data |

Memory Map of STM32L4



AVR Memory Map: ATmega168

Access is encoded by commands with address operands that uniquely identify specific memory locations.

So far, we have used several commands to access the SRAM register locations, GP Regs, I/O Regs, Intern SRAM locations:

GP Register Commands

| | |
|------------|--------------------|
| clr Rd | clear register |
| dec Rd | decrement register |
| inc Rd | increment register |
| ser Rd | set register |
| mov Rd, Rr | copy register |

Commands for Upper SRAM Addr Locations

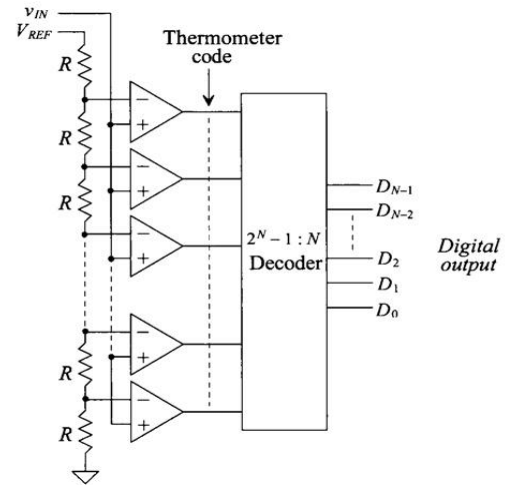
| | |
|-----------|--|
| ldi Rd, K | Load immediate data K into GP Reg |
| ld Rd, k | Load indirect from addr k into GP Reg |
| sts k, Rr | store direct to data addr k from GP Reg |
| st X, Rr | store indirect to data addr within X from GP Reg |

ADC Types

Flash ADC

For an N-bit Flash ADC
 requires 2^N resistors in a string ladder resistor divider
 requires $2^N - 1$ comparators
 requires 2^N to N priority encoder logic with 'bubble error' detect/correct
 8 to 3 priority encoder for 3-bit conversion
 16 to 4 priority encoder for 4-bit conversion
 256 to 8 priority encoder for 8-bit conversion
 Several techniques to detect/correct 'bubble error'
 > 8bits decreasingly practical,

Pos fastest ADC - maybe 10 nS delay time, simple concept
 Neg But requires $2^N - 1$ comp & 2^N res which limit resolution



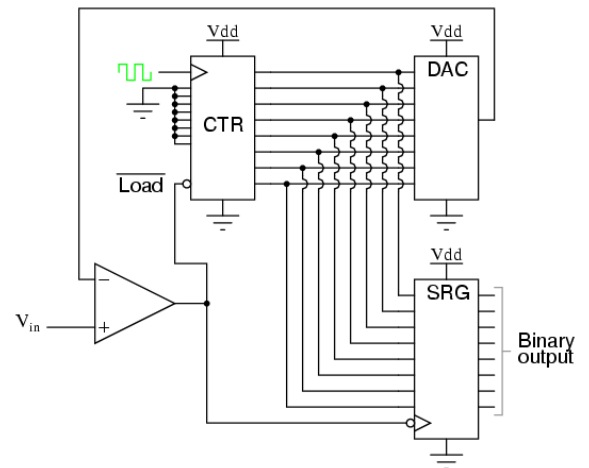
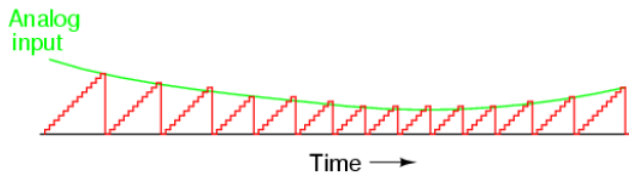
Digital Ramp ADC

Counter up-counts
 DAC stair-steps V_{DAC} until it reaches the V_{IN} threshold.
 Then the counter resets, V_{DAC} goes to zero, conversion starts again

$$T_{CONV} \text{ of each sample} = (V_{IN}/V_{LSB}) * t_{CLK} = V_{IN}/(V_{REF}/2^N) * t_{CLK}$$

$$= 2^N * (V_{IN}/V_{REF}) * t_{CLK}$$

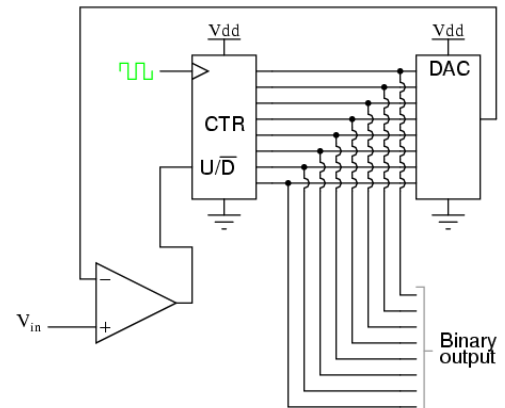
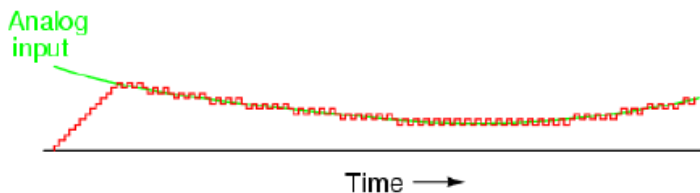
Pos simple design concept, low cost implementation
 clk can decrease conversion time, typ faster than dual slope
 Neg But still a slower technique, requires DAC, variable conversion time,



Tracking ADC

Similar to the Dig Ramp ADC, uses U/D counter
 Faster sustained conversion, initial conv ramp is visible at the output,
 a conversion every clk is possible for slow signals,
 exhibits bit bobble at a constant V_{in}

Pos faster conv after init ramp, 1 clk updates possible, simple concept, clk controls conver time
 Neg but requires DAC, output dithers 1LSB with a stable input

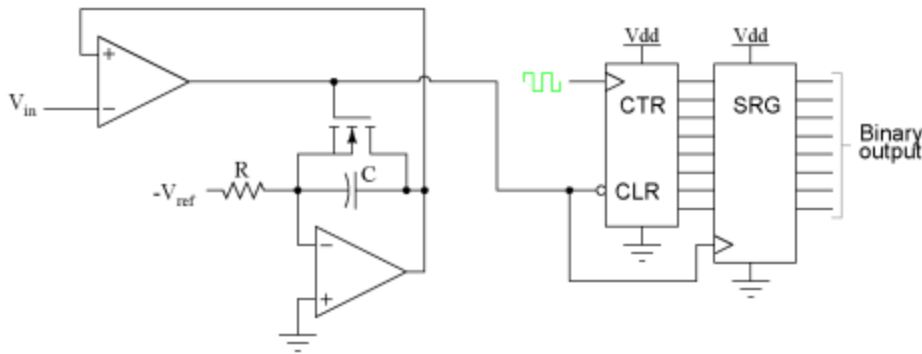


Single-Slope ADC

Similar to the Dig Ramp ADC, replaces the DAC with an Inv Integrator, conversion time = integration time

Pos No DAC, simple design, low cost, clk can decrease conver time

Neg But still a slower technique, variable conversion time, must be calibrated - integ time must = FS cnt time, and analog component values may drift



What is the integ time? ($t_{INT}=t_{CONV}$)

Remember $V=Q/C$?

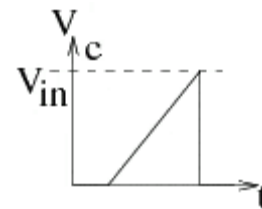
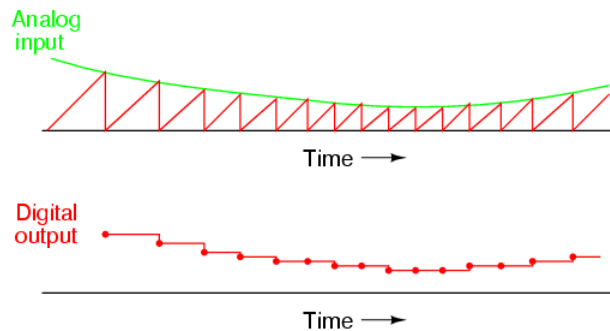
$$V_{CAP} = I * t / C \quad (\text{sub } I * t \text{ for } Q)$$

$$V_{OUT} = -(V_{REF}/R) \cdot t / C \quad (\text{sub } V_{REF}/R \text{ for } I)$$

$$t = -V_{OUT} * R * C / V_{REF} \quad (\text{solve for } t)$$

$$t = -V_{IN} * R * C / V_{REF} \quad (V_{OUT} = V_{IN} @ \text{EOC})$$

Time required for the integrator V_{OUT} to reach V_{IN} is the conversion time.



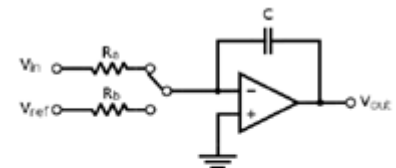
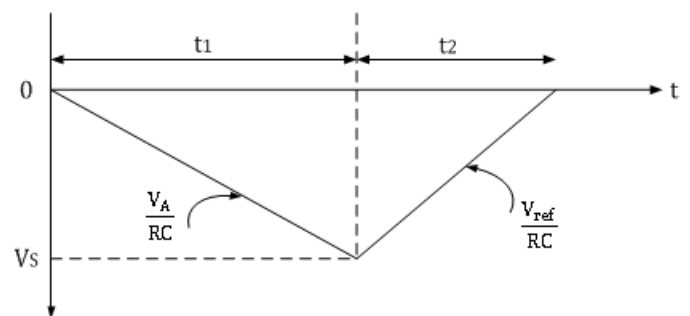
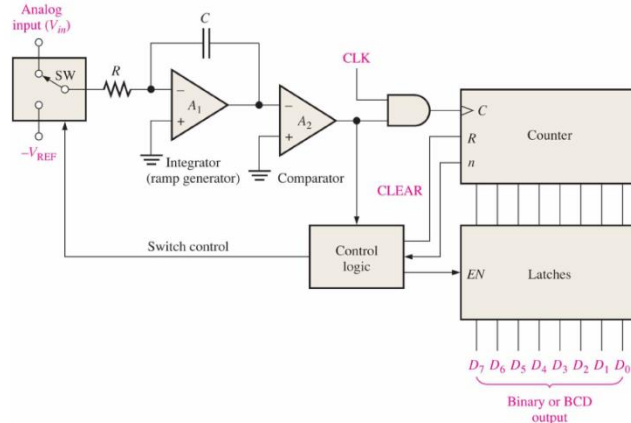
Dual-Slope ADC

$$V_{IN} * t_{INT} = V_{REF} * t_{DE-INT} \quad T_{CONV} = t_{INT} + t_{DE-INT} \quad t_{DE-INT} = t_{CLK} * (Cntr\ Out)_d \quad (\text{dec equiv of counter output})$$

Slow ... but, averaging reduces noise, good linearity, no drift, high resolution achievable, good accuracy, immune to comp drift

Pos No DAC, simple design, low cost, clk can decrease conver time, no drift error

Neg But still a slower technique, variable conversion time



Enhanced Dual-Slope ADC

$$V_S = (V_A/R_A) * t_1 / C = (V_{REF}/R_B) * t_2 / C$$

$$(V_A/R_A) * t_1 = (V_{REF}/R_B) * t_2$$

$$0 = V_{OUT1} + V_{OUT2}$$

$$= -(V_{IN}/R)*t_1/C + [-(V_{REF}/R)*t_2/C]$$

$$\Rightarrow (V_{IN}/R) \cdot t_1 / C = -(V_{REF}/R) \cdot t_2 / C$$

$$V_{IN} * t_1 = |V_{REF}| * t_2$$

$$V_A * t_{INT} = |V_{REF}| * t_{DE-INT}$$

$$V_A/V_{REF} = t_2 / t_1$$

$$T_{\text{CONV}} = t_{\text{INT}} + t_{\text{DE-INT}}$$

Example

For an analog $V_{IN} = 2.5V$ and $V_{REF} = 5V$ and $t_{INT} = 10mS$ What is the total conversion time?

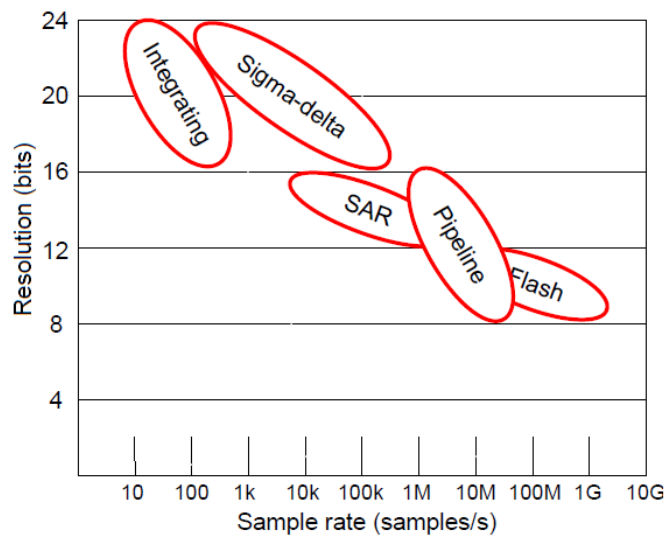
$$t_{DE-INT} = (V_{IN}/|V_{REF}|) * t_{INT}$$

$$\text{Total Conv time} = t_{INT} + t_{DE-INT} = 10mS + 10mS * (2.5/5) = 10mS + 5mS = 15mS$$

What is the Counter output?

$$\text{Cntr Out} = (t_{DE-INT}/t_{CLK})_b \quad (\text{Counter Out is the binary equiv of the decimal ratio } t_{DE-INT}/t_{CLK})$$

ADC Performance Comparison: LECTURE-AD_Conversion_Part2_Wk2 Pg 42



- Flash (or Simultaneous)
- (where are Digital Ramp and Tracking?)
- Integrating (Single-slope and Dual-slope)
- SAR (Successive approximation register)
- Pipeline (Subranging or Half-flash)
- Sigma-delta